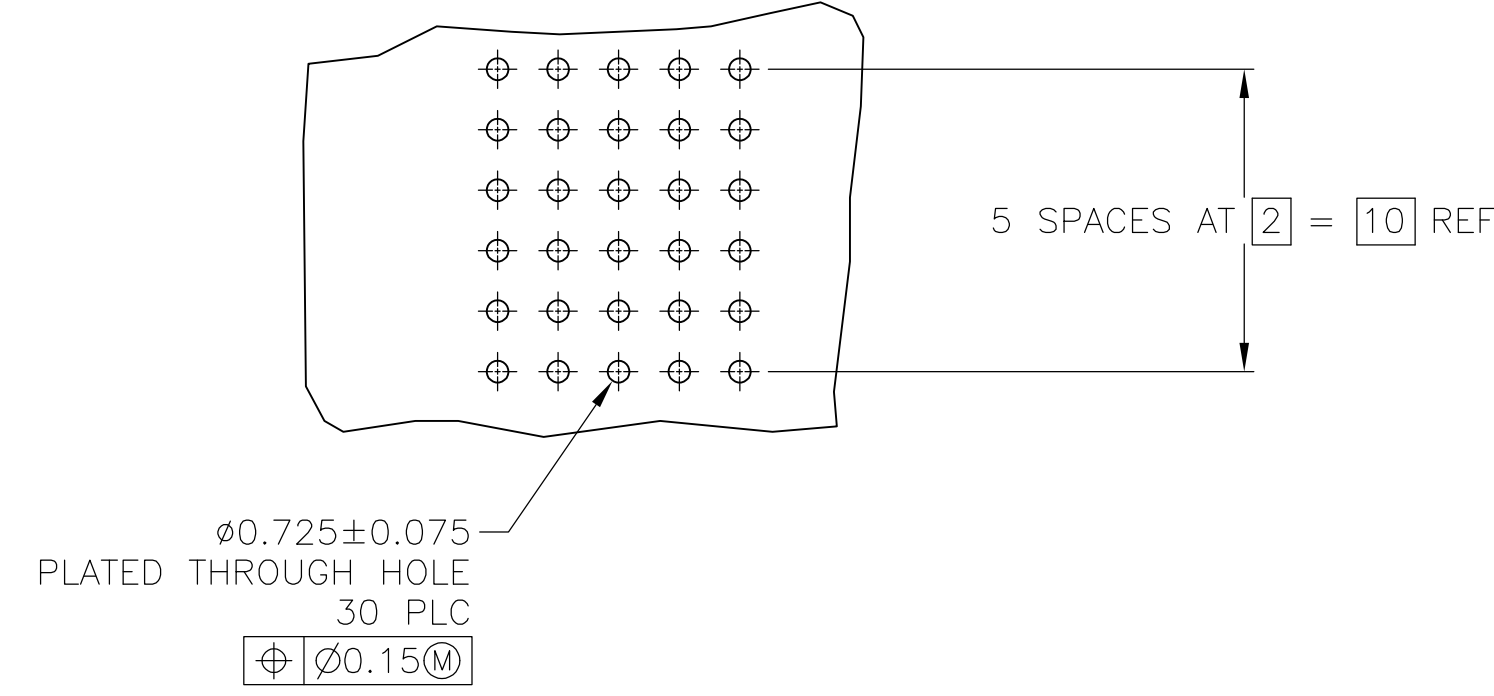
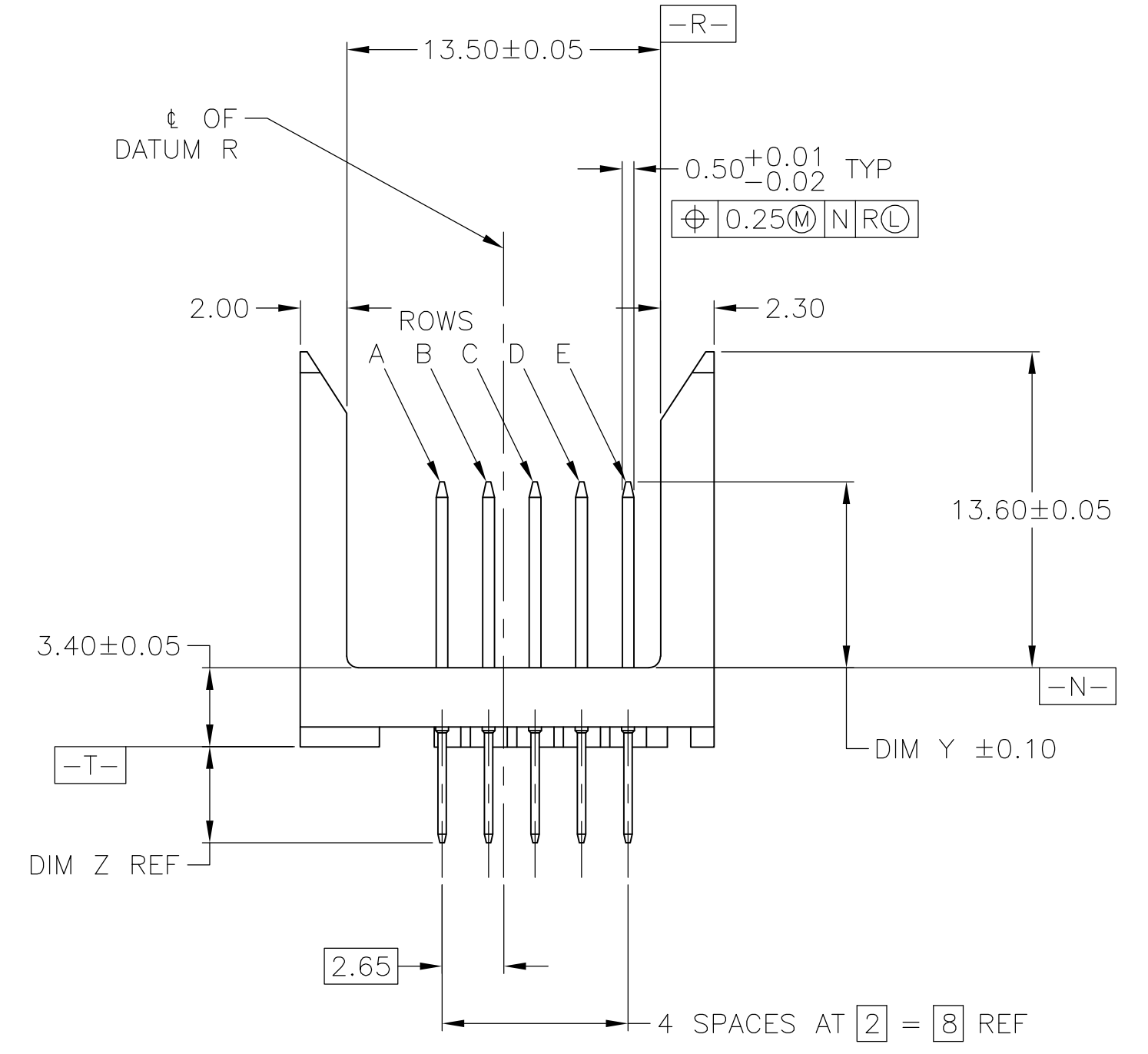
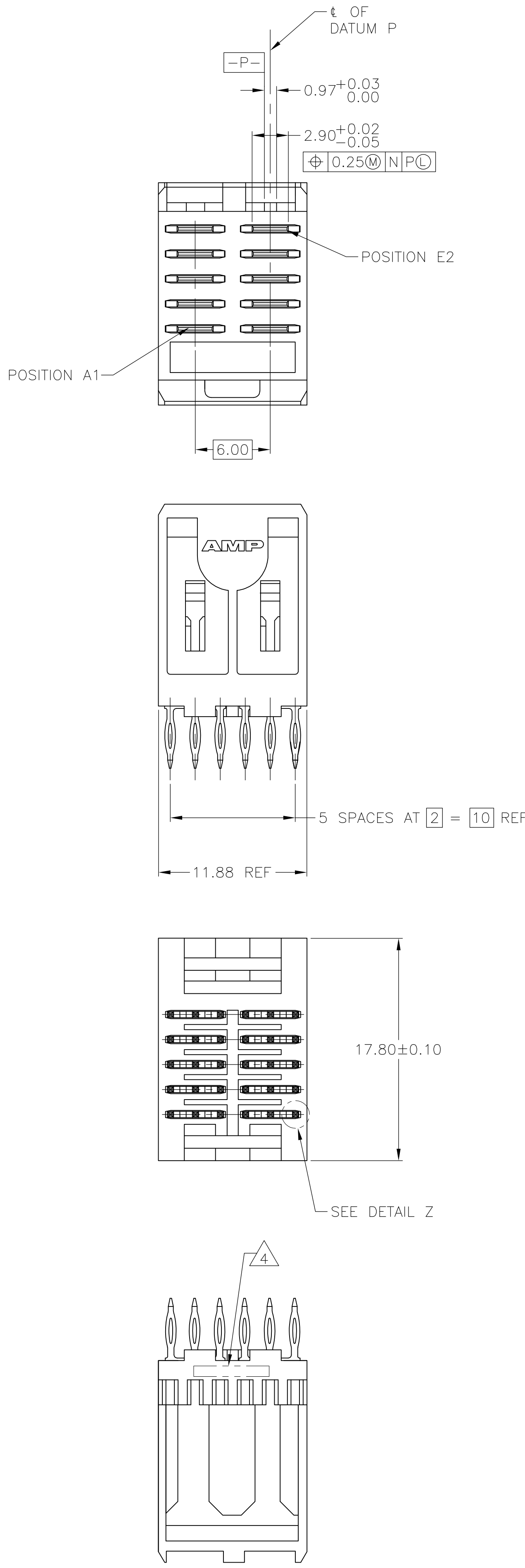


D

C

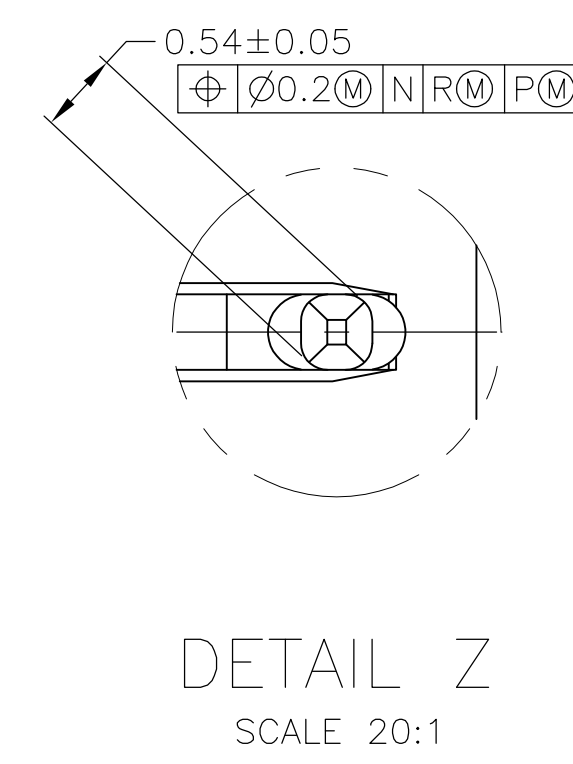
B

A



RECOMMENDED CIRCUIT PATTERN
PER IPC-D300 TYPE II, CLASS C
(COMPONENT SIDE)

- 1 HOUSING MATERIAL: LIQUID CRYSTAL POLYMER, NATURAL.
- 2 CONTACT MATERIAL: COPPER ALLOY.
- 3 CONTACT FINISH:
UNDERPLATE (ENTIRE CONTACT):
0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290
ON MATING SURFACES:
FLASH GOLD PER ASTM B 488, OVER
0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR
0.00076 MIN GOLD PER ASTM B 488 OVER UNDERPLATE.
ON LEADS:
0.00127 MIN TIN-LEAD OVER UNDERPLATE.
LUBRICATION (MIN MATING SURFACES):
SURFACE CONDITIONER AFTER PLATING.
- 4 PART NUMBER AND DATE CODE IN APROXIMATE AREA AS SHOWN.
- 5 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN T. SHUEY 1-7-98		TE Connectivity	
DIMENSIONS: mm		CHK W. MILLHIMES 1-16-98			
		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME	
		0 PLC ± - 1 PLC ± - 2 PLC ± - 3 PLC ± - 4 PLC ± - ANGLES ± - ± - FINISH		PRODUCT SPEC 108-1441 APPLICATION SPEC 114-1075	
MATERIAL 1 2		WEIGHT -		SIZE A1	
		CUSTOMER DRAWING		SCALE 4:1 SHEET 1 OF 2 REV R4	

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